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FOR IMMEDIATE RELEASE

Press Release

An Innovation Reliability Solution to Interconnect of Flexible/Rigid Substrates

(**Albany, NY) July 25, 2014 –** Miniaturization is a trend in the electronic industry, which has increasingly attracted more attention. However, the manufacturing process and reliability have become more and more challenging due to miniaturization. The main issues that miniaturization present are the strength of solder joints, decreasing thermal cycling performance, and product reworkability.

Increasing miniaturization in the electronic industry is a trend that can clearly be seen as time continues to move forward. The strength of solder joint or interconnects presents a challenging issue as it becomes more difficult to meet customers' requirements. Underfilling the interconnects of rigid/flexible substrates does not solve the problem. SMT 266 - Solder joint encapsulant adhesive provides a reliable solution to the interconnect of rigid/flexible substrates. Using solder joint encapsulant adhesive not only doubles the strength of the interconnect compared to using traditional flux, but also ensures 100% manufacturing process yield. SMT 266 is used in line process, thus shortening the manufacturing process. The SMT 266 solder joint encapsulant adhesive provides a solution to all problems that miniaturization can cause.

Additional information regarding SMT 266 is available by contacting YINCAE at info@yincae.com.

If you wish to visit the official website of YINCAE Advanced Materials, LLC, please visit us by clicking the following link: YINCAE Website.

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Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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